ASSOCIATION CONNECTING ASSOCIATION CONNECTING LECTRONICS INDUSTRIES	IPC. Bannockl	burn, Illinois, A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declarati the declaration e	on of the su	ibstances v s all lower	within the manufact level materials for	urer listed which the	item. Note: manufacture	if the item is an as er has engineering	ssembly with low responsibility.	
				Form Type Distribute					rials and I	ials and Mfg Information				
Supplier Information														
Company name*		Company unique ID			-	Unique ID Authority				Respo	Response Date*			
onsemi										2024-0	2024-05-17			
Contact Name Title - Co			ele - Contact			Phone - Contact*				Email	Email - Contact*			
Product-Env-Stewards Produ			Product Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Authorized Representative* Title			Title - Representative			Phone - Representative*				Email	Email - Representative*			
Product-Env-Stewards Pr			Product Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Iten	Number Mfr Item Name				Effective Date	Date Version Manufactur		Ianufacturing Site	Weight*		UOM	Unit Type	
	NRVUS	NRVUS2MA HER SMA GPP		N 1.5A 1000V		2024-05-17		Т	TSCBE		64.016	mg	Each	
Aanufacturing Proccess Informa	ation													
Terminal Plating / Grid Array M	Iaterial 7	Ferminal Base	Alloy	J-STD-020 MSL Rating		Peak Proce	Peak Process Body Temperat		ure Max Time at Peak Tempe		ature Num	ber of Reflow Cy	cles	
Matte Tin (Sn) - annealed Cl		CU Alloy	loy 1			260	260 C		30	seco	onds 3			
omments														
vel 1 - maximum time at peak temperat	ture during so	ldering is 10-3	0 seconds											
or more information regarding materia	l composition	please refer to	page 3											

RoHS Material Composition Declar	ation			Declaration Type *	Detailed
Directive 2015/863/EU amending Rol Directive 2011/65/EU	(Pb), Mercury (Hg), Hexav		ninated Biphenyls (PBB), Polybror	dmium and quantity limit of 0.1% by mass (100 ninated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polyb contains a RoHS restricted substance i encompass all such components.Suppl as of the date that Supplier completes Company acknowledges that Supplier independently verified information pro- certification in this paragraph.If the Co	rominated biphenyls and/or polybror nexcess of an applicable quantity lim ier certifies that it gathered the inforr this form.Supplier acknowledges that may have relied on informationprovi ovided by others, Supplier agrees that ompany and the Supplier enter into a clusivesource of the Supplier's liabili	ninated diphenyl ethers (each a "R it, please indicate below which, if nation it provides in this form usin Company will rely on this certifud ded by others in completing this f , at a minimum, itssuppliers have written agreement with respect to ty and the Company's remedies for	toHS restricted substance") in exce any, RoHS exemption you believe ag appropriate methods to ensure it cation in determining the complian orm, and that Supplier may not hav provided certifications regarding th the identified part,the terms and co or issues that arise regarding inform	ropean Union member states) of the part identifies so of the applicable quantity limit identified about may apply. If the part is an assembly with lows a accuracy and that such information is true and ce of its products with European Union member re independently verified such information. How heir contributions to the part, and those certifica motions of that agreement, including any warra nation the Supplier provides in this form. In the	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the inty rights and/or remedies provided as part of
RoHS Declaration * 4	- Item(s) does not contain RoHS restr	icted substances per the definition	above except for selected exempti	ons Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high meltin Exemption: 7c-I Electrical and elect	g temperature type solders (i.e. lead ronic components containing lead i	l based solder alloys containing n a glass or ceramic other than	85% by weight or more lead). dielectric ceramic in capacitors, o	e.g. piezoelectronic devices, or in a glass or ce	eramic matrix compound.
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the rec Requester) and click on Submit For			Supplier Acceptance drop-down	. This will display the signature area. Digital	ly sign the declaration (if required by the
Supplier Digital Signature	Rastislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.28	mg	А	Lead (Pb)	7439-92-1	7c	0.0614	mg
			Supplier	Silicon (Si)	7440-21-3		1.2006	mg
			В	Nickel (Ni)	7440-02-0		0.0115	mg
			Supplier	Gold (Au)	7440-57-5		0.0064	mg
Die Attach Solder	2.098	mg	Supplier	Silver (Ag)	7440-22-4		0.0525	mg
			А	Lead (Pb)	7439-92-1	7a	1.9407	mg
			Supplier	Tin (Sn)	7440-31-5		0.1049	mg
Lead Frame	18.636	mg	Supplier	Iron (Fe)	7439-89-6		0.024	mg
			Supplier	Copper (Cu)	7440-50-8		18.6	mg
			Supplier	Phosphorus (P)	7723-14-0		0.012	mg
Mold Compound-Black	41.002	mg		Metal Hydroxide	proprietary data		3.0752	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		6.1503	mg
			Supplier	Carbon Black (C)	1333-86-4		0.205	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		28.2914	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		3.2802	mg
Plating	1.0	mg	Supplier	Tin (Sn)	7440-31-5		1	mg